Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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30V DUAL N AND P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

Device	$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
N-Channel	30V	0.135Ω	2.3A
P-Channel	-30V	0.185Ω	-2.0A

Features

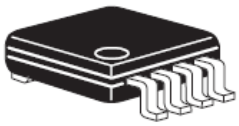
- Low On-resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Low Profile SOIC Package

Description

This new generation of high density MOSFETs from Diodes Incorporated utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

Applications

- DC - DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control



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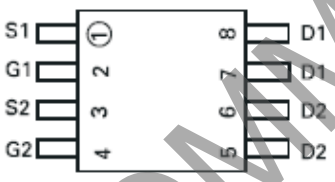
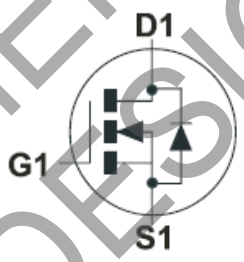
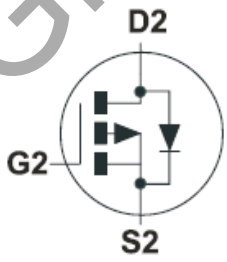


Pin-Out
Top View



N-channel



P-channel

Ordering Information

Part Number	Device Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
ZXMD63C03XTA	ZXM63C03	7	12mm Embossed	1000 Units
ZXMD63C03XTC	ZXM63C03	13	12mm Embossed	4000 Units

Maximum Ratings

PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain-Source Voltage	V_{DSS}	30	-30	V
Gate- Source Voltage	V_{GS}	±20		V
Continuous Drain Current (V_{GS}=4.5V; T_A=25°C)(b)(d) (V_{GS}=4.5V; T_A=70°C)(b)(d)	I_D	 2.3 1.8	 -2.0 -1.6	 A A
Pulsed Drain Current (c)(d)	I_{DM}	14	-9.6	A
Continuous Source Current (Body Diode)(b)(d)	I_S	1.5	-1.4	A
Pulsed Source Current (Body Diode)(c)(d)	I_{SM}	14	-9.6	A
Power Dissipation at T_A=25°C (a)(d) Linear Derating Factor	P_D	0.87 6.9		W mW/°C
Power Dissipation at T_A=25°C (a)(e) Linear Derating Factor	P_D	1.04 8.3		W mW/°C
Power Dissipation at T_A=25°C (b)(d) Linear Derating Factor	P_D	1.25 10		W mW/°C
Operating and Storage Temperature Range	T_j:T_{stg}	-55 to +150		°C

Thermal Characteristics

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(d)	$R_{\theta JA}$	143	°C/W
Junction to Ambient (b)(d)	$R_{\theta JA}$	100	°C/W
Junction to Ambient (a)(e)	$R_{\theta JA}$	120	°C/W

NOTES:

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

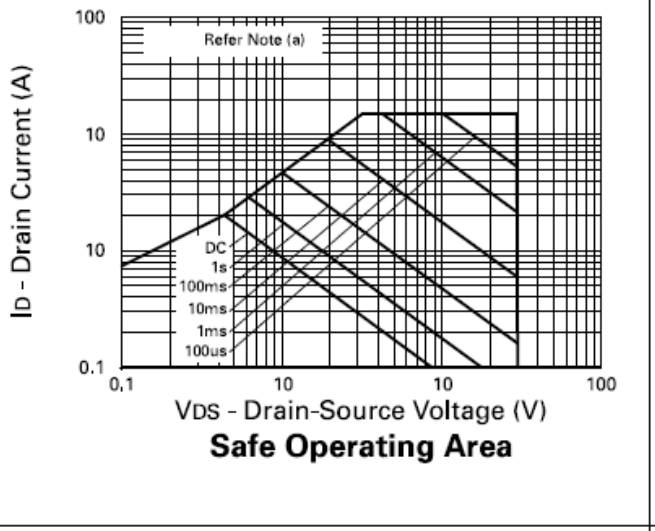
(b) For a device surface mounted on FR4 PCB measured at t≤10 secs.

(c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

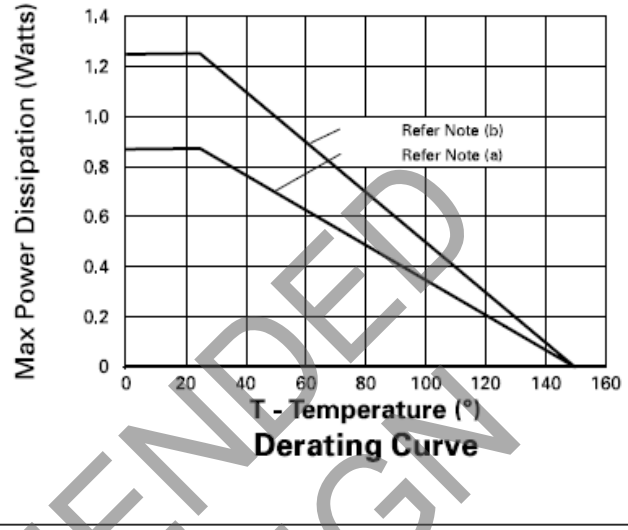
(d) For device with one active die.

(e) For device with two active die running at equal power.

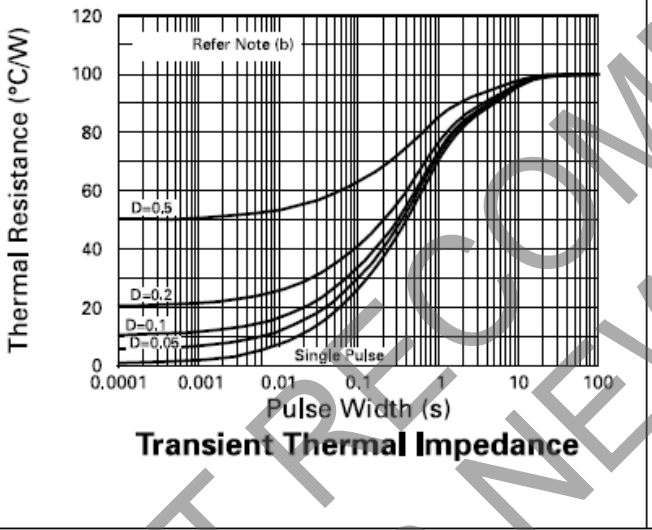
N-Channel Characteristics



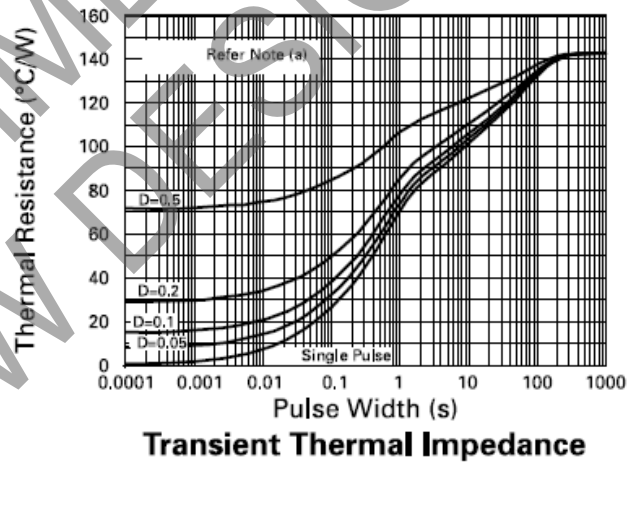
Safe Operating Area



Derating Curve

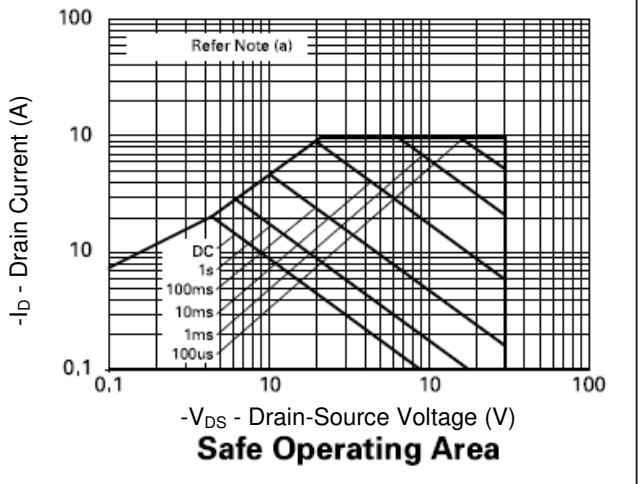


Transient Thermal Impedance

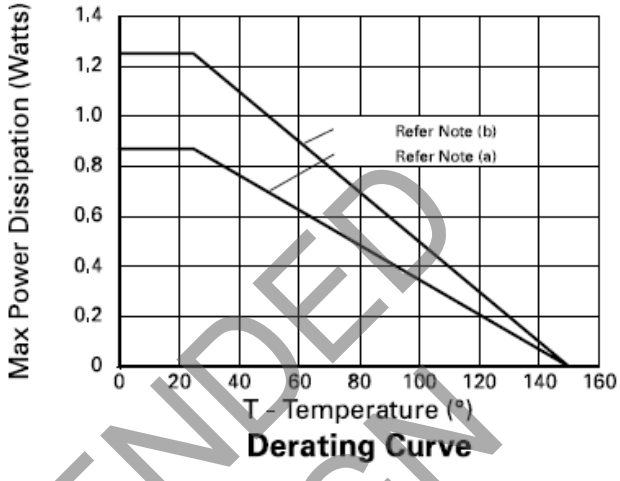


Transient Thermal Impedance

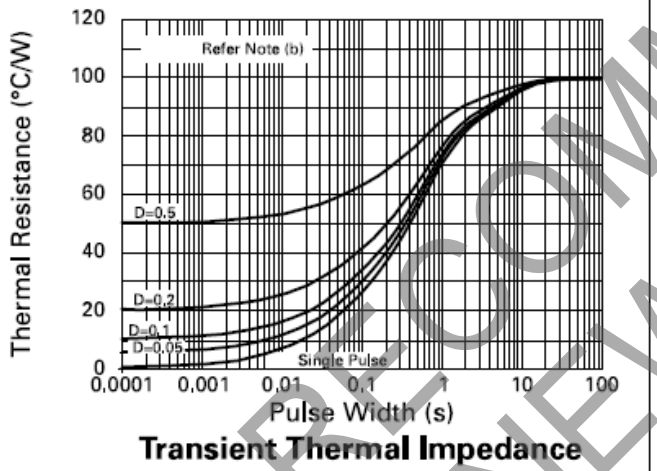
P-Channel Characteristics



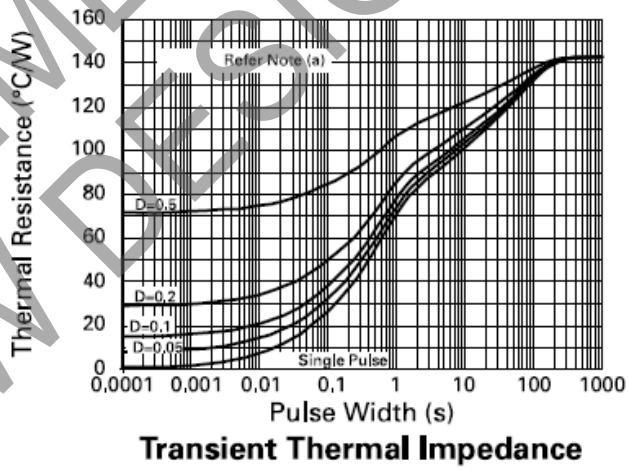
Safe Operating Area



Derating Curve



Transient Thermal Impedance



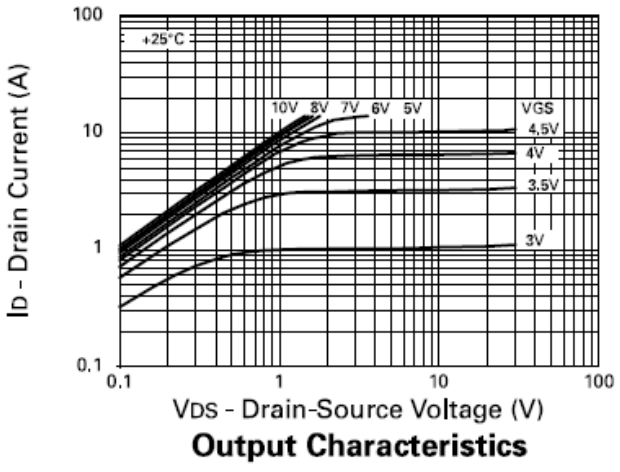
Transient Thermal Impedance

Electrical Characteristics – N-Channel (@T_A = +25°C, unless otherwise specified.)

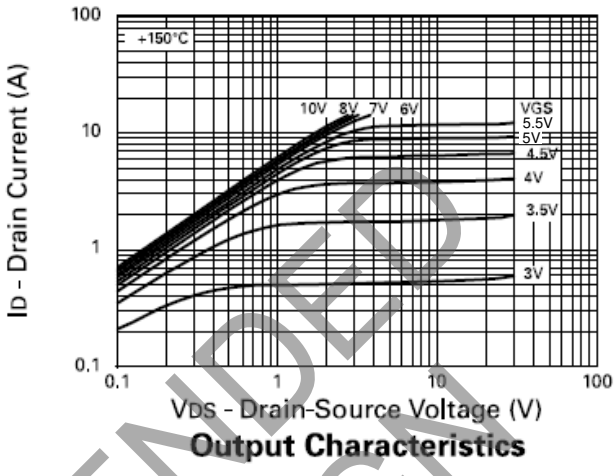
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30			V	I_D=250µA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			1	µA	V_{DS}=30V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			100	nA	V_{GS}=± 20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0			V	I_D=250µA, V_{DS}= V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.135 0.200	Ω Ω	V_{GS}=10V, I_D=1.7A V_{GS}=4.5V, I_D=0.85A
Forward Transconductance (3)	g_{fs}	1.9			S	V_{DS}=10V,I_D=0.85A
DYNAMIC (3)						
Input Capacitance	C_{iss}		290		pF	V_{DS}=25 V, V_{GS}=0V, f=1MHz
Output Capacitance	C_{oss}		70		pF	
Reverse Transfer Capacitance	C_{rss}		20		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		2.5		ns	V_{DD} =15V, I_D=1.7A R_G=6.1Ω, R_D=8.7Ω (Refer to test circuit)
Rise Time	t_r		4.1		ns	
Turn-Off Delay Time	$t_{d(off)}$		9.6		ns	
Fall Time	t_f		4.4		ns	
Total Gate Charge	Q_g			8	nC	V_{DS}=24V,V_{GS}=10V, I_D=1.7A (Refer to test circuit)
Gate-Source Charge	Q_{gs}			1.2	nC	
Gate Drain Charge	Q_{gd}			2	nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}			0.95	V	T_j=25°C, I_S=1.7A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		16.9		ns	T_j=25°C, I_F=1.7A, di/dt= 100A/µs
Reverse Recovery Charge(3)	Q_{rr}		9.5		nC	

NOTES:
(1) Measured under pulsed conditions. Width=300µs. Duty cycle ≤2%.
(2) Switching characteristics are independent of operating junction temperature.
(3) For design aid only, not subject to production testing.

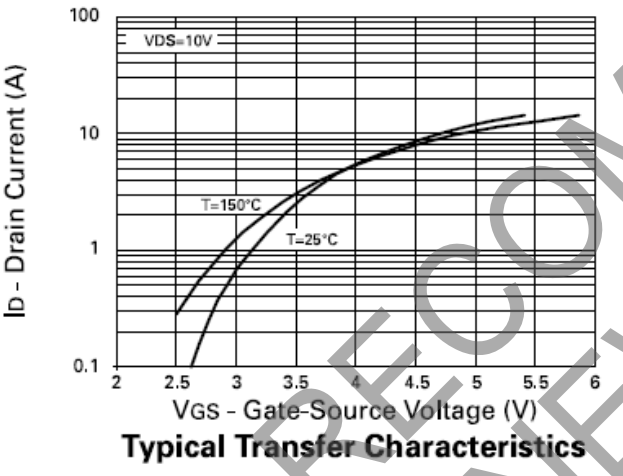
N-Channel Typical Characteristics



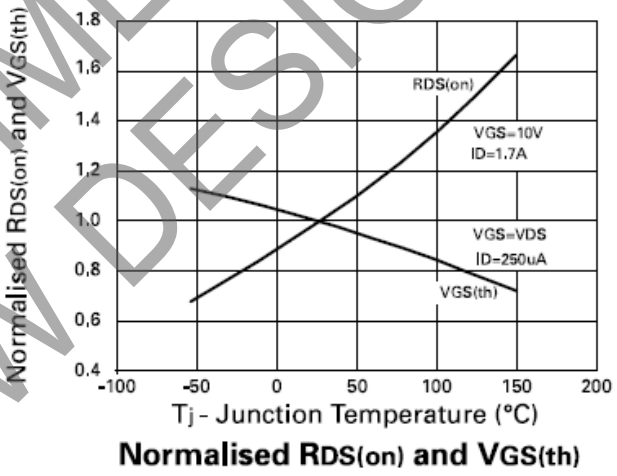
Output Characteristics



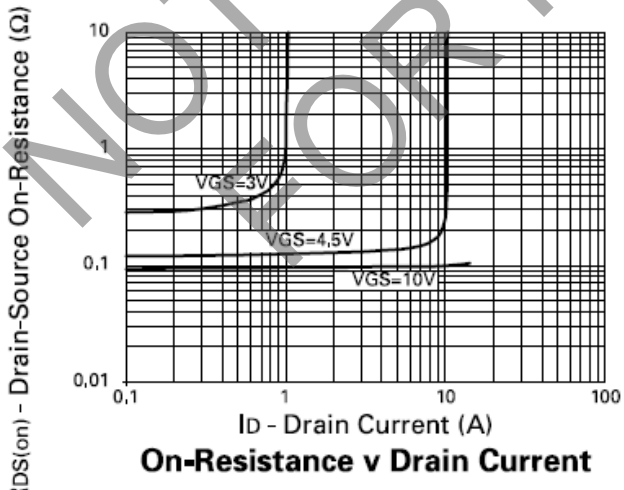
Output Characteristics



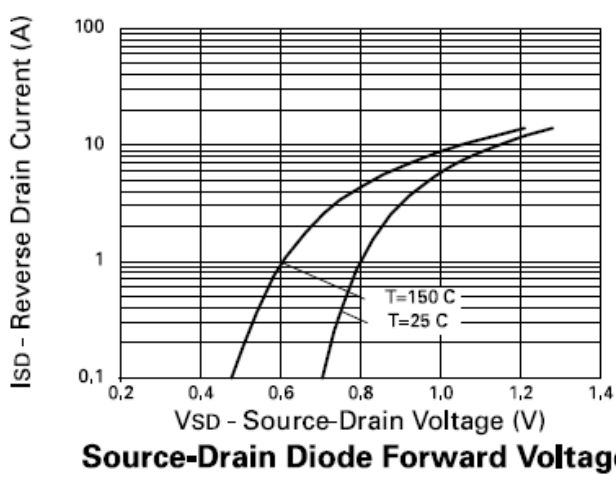
Typical Transfer Characteristics



Normalised RDS(on) and VGS(th) v Temperature

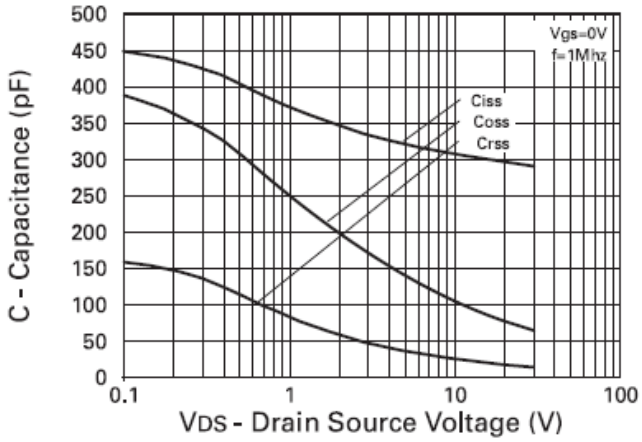


On-Resistance v Drain Current

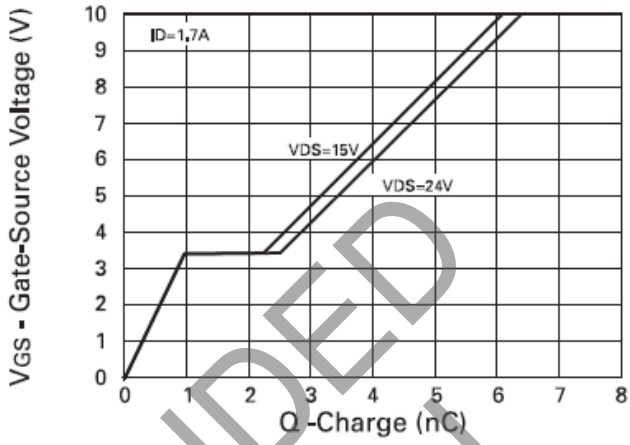


Source-Drain Diode Forward Voltage

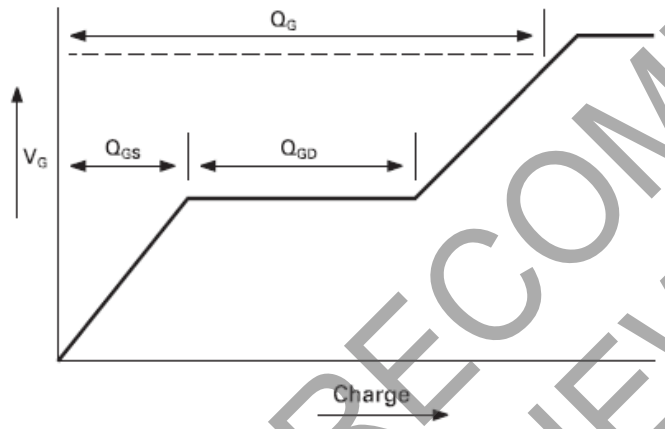
N-Channel Characteristics



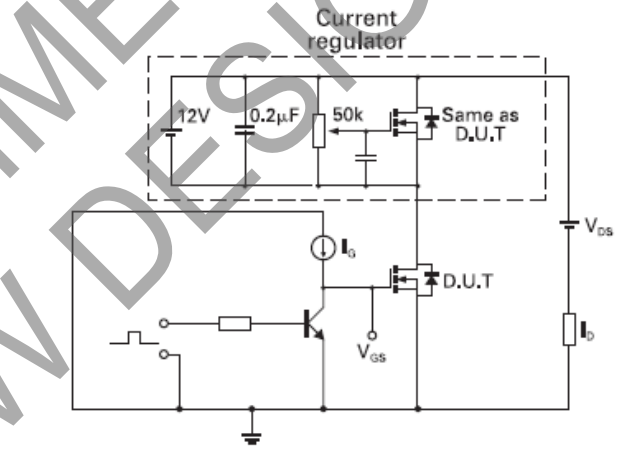
Capacitance v Drain-Source Voltage



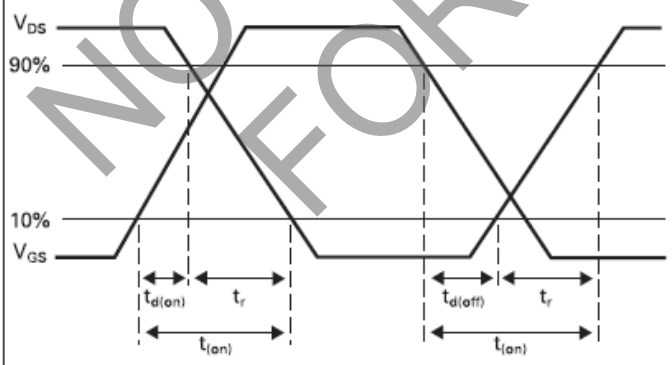
Gate-Source Voltage v Gate Charge



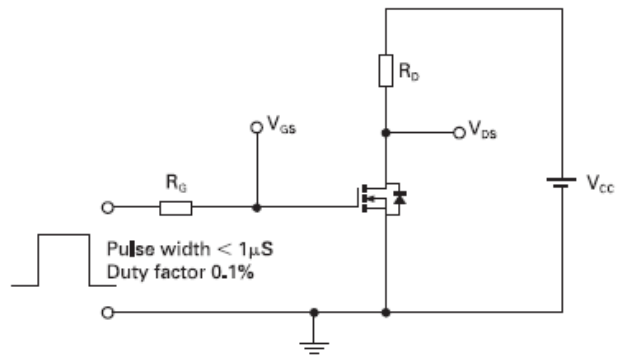
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms



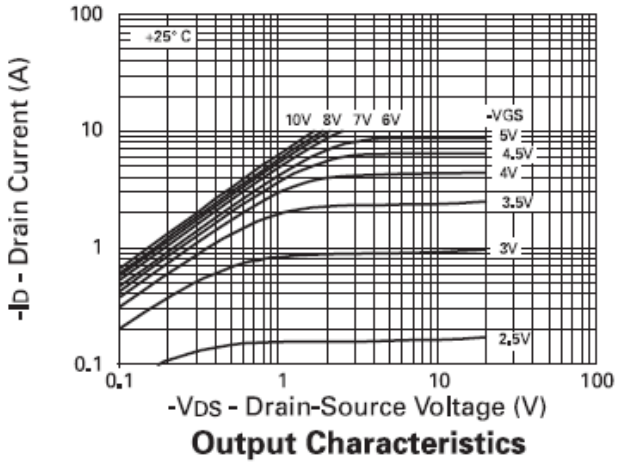
Switching time test circuit

Electrical Characteristics – P-Channel (@T_A = +25°C, unless otherwise specified.)

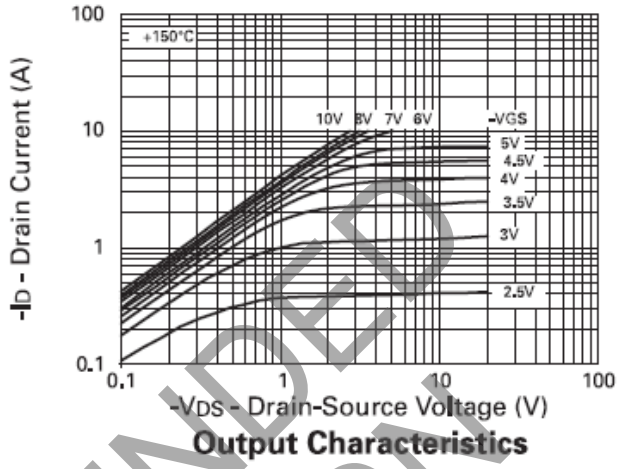
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-30			V	I_D=-250µA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			-1	µA	V_{DS}=-30V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			±100	nA	V_{GS}=±20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	-1.0			V	I_D=-250µA, V_{DS}=V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.185 0.27	Ω Ω	V_{GS}=-10V, I_D=-1.2A V_{GS}=-4.5V, I_D=-0.6A
Forward Transconductance (3)	g_{fs}	0.92			S	V_{DS}=-10V, I_D=-0.6A
DYNAMIC (3)						
Input Capacitance	C_{iss}		270		pF	V_{DS}=-25 V, V_{GS}=0V, f=1MHz
Output Capacitance	C_{oss}		80		pF	
Reverse Transfer Capacitance	C_{rss}		30		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		2.6		ns	V_{DD} =-15V, I_D=-1.2A R_G=6.2Ω, R_D=6.2Ω (Refer to test circuit)
Rise Time	t_r		4.8		ns	
Turn-Off Delay Time	$t_{d(off)}$		13.1		ns	
Fall Time	t_f		9.3		ns	
Total Gate Charge	Q_g			7	nC	V_{DS}=-24V, V_{GS}=-10V, I_D=-1.2A (Refer to test circuit)
Gate-Source Charge	Q_{gs}			1.2	nC	
Gate Drain Charge	Q_{gd}			2	nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}			-0.95	V	T_J=25°C, I_S=-1.2A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		21.4		ns	T_J=25°C, I_F=-1.2A, di/dt= 100A/µs
Reverse Recovery Charge(3)	Q_{rr}		15.7		nC	

NOTES:
(1) Measured under pulsed conditions. Width=300µs. Duty cycle ≤2% .
(2) Switching characteristics are independent of operating junction temperature.
(3) For design aid only, not subject to production testing.

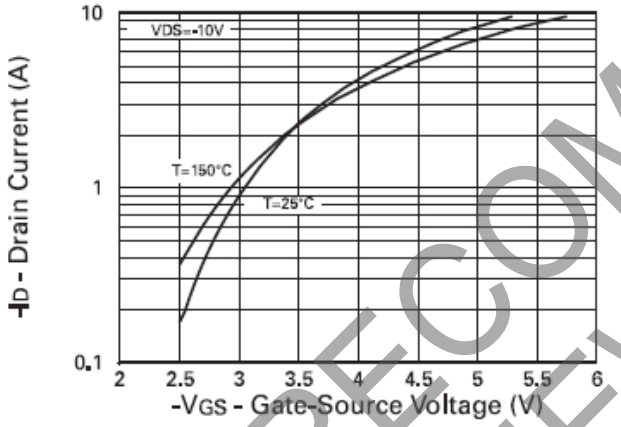
P-Channel Characteristics



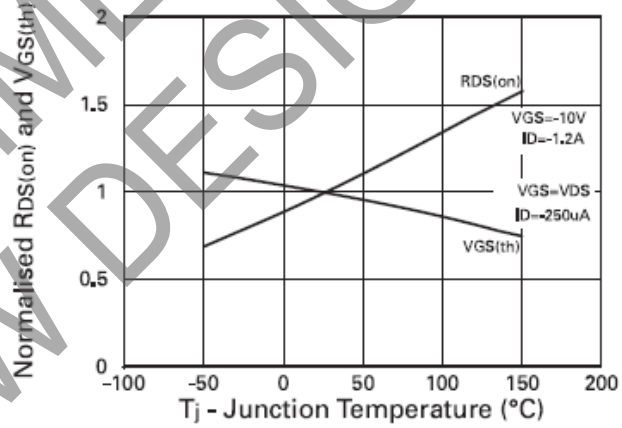
Output Characteristics



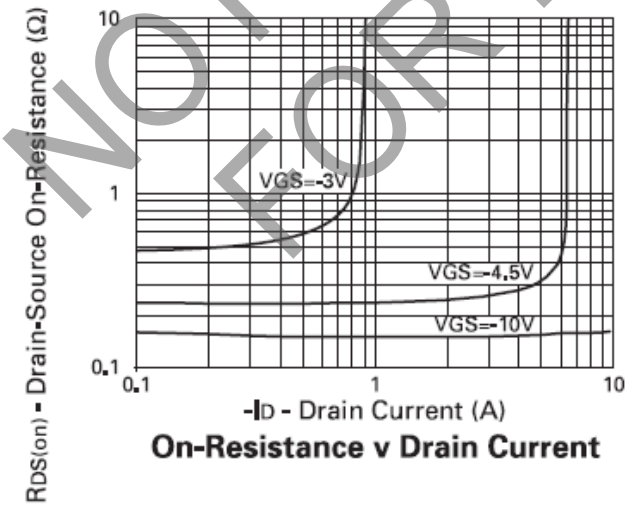
Output Characteristics



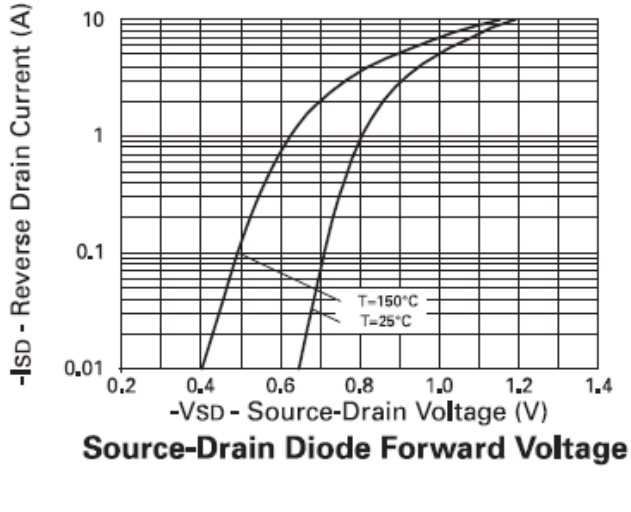
Typical Transfer Characteristics



Normalised RDS(on) and VGS(th) v Temperature

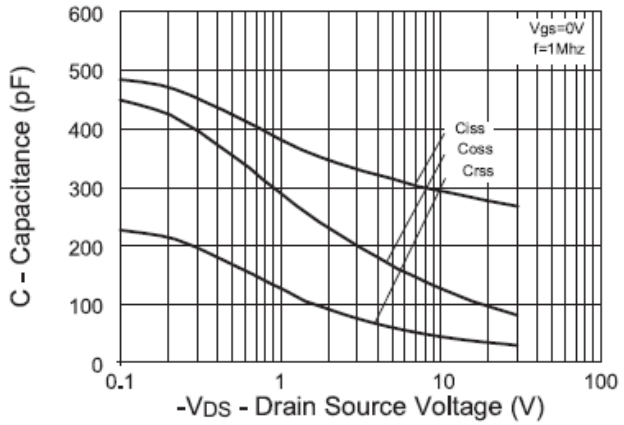


On-Resistance v Drain Current

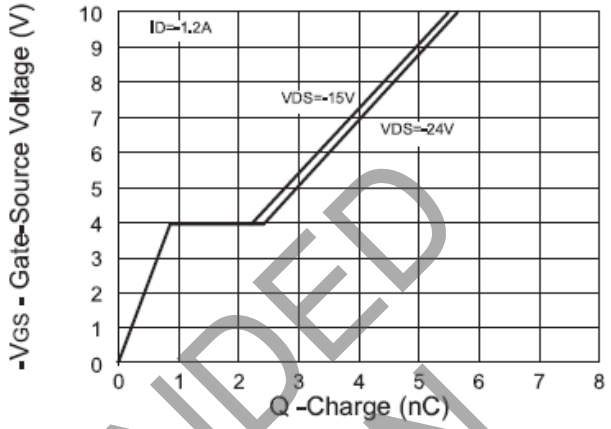


Source-Drain Diode Forward Voltage

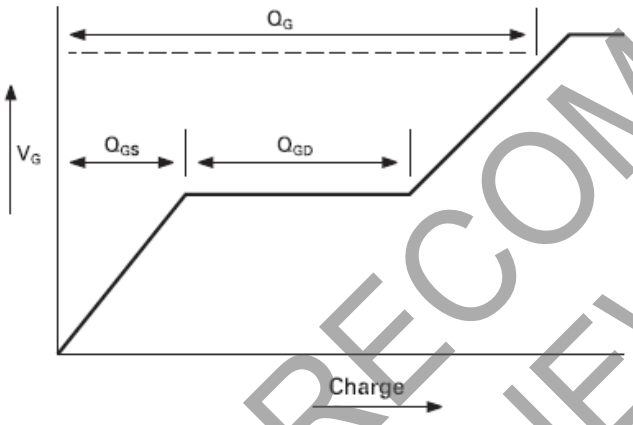
P-Channel Typical Characteristics



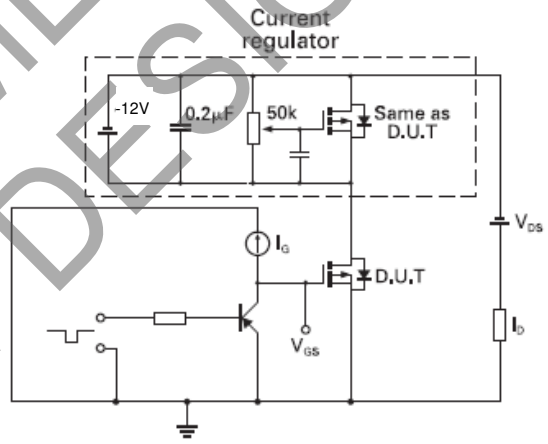
Capacitance v Drain-Source Voltage



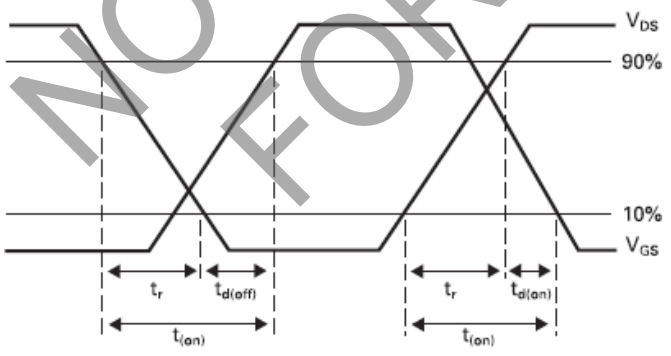
Gate-Source Voltage v Gate Charge



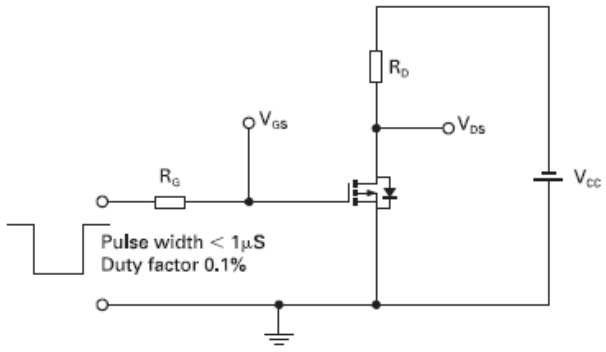
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

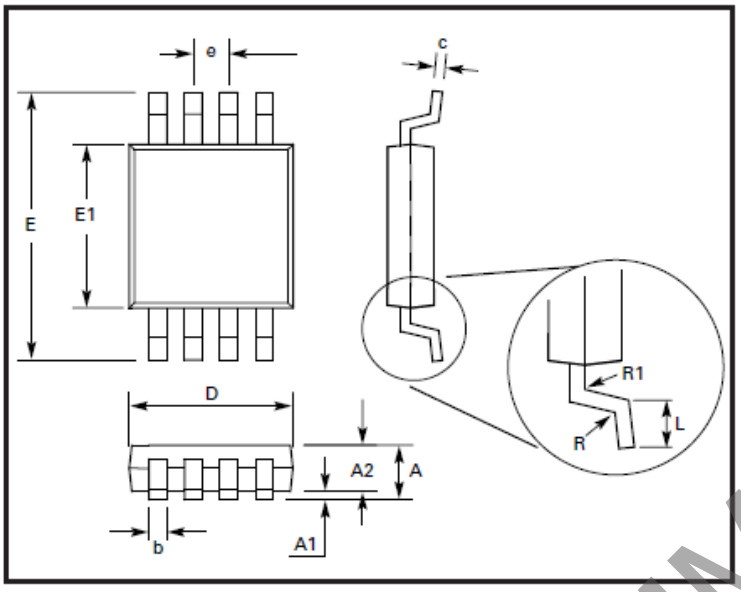


Switching time test circuit

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

MSOP8

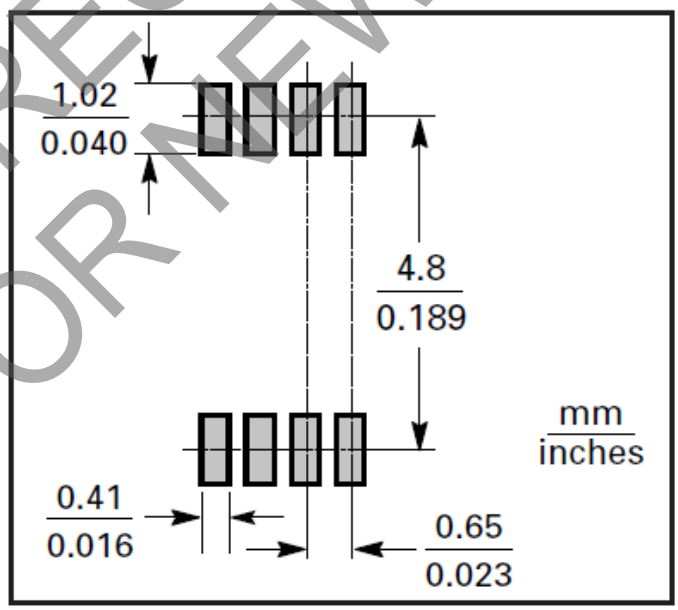


DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	-	1.10	-	0.0433
A1	0.05	0.15	0.002	0.006
A2	0.75	0.95	0.0295	0.0374
b	0.25	0.40	0.010	0.0157
c	0.13	0.23	0.005	0.009
D	2.90	3.10	0.114	0.122
E	4.90 BSC		0.193 BSC	
E1	2.90	3.10	0.114	0.122
e	0.65 BSC		0.025 BSC	
L	0.40	0.70	0.0157	0.0192
R	0.07	-	0.0027	-
R1	0.07	-	0.0027	-

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

MSOP8



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